L Number	Hits	Search Text	DB	Time stamp
1	1196	(polish$3 abrad$3 planari$6)with immers$4	USPAT	2004/04/02 08:08
2	0	((polish$3 abrad$3 planari$6)with immers$4)same magnet$6 adj3 (solution agent)	USPAT	2004/04/02 08:10
3	23	(magnet$6 adj4 (polish$3 planariz$6) adj4 (solution agent))	USPAT	2004/04/02 08:10
–	567	156/345.12 156/345.13 156/345.17 156/345.18 156/345.23	USPAT	2004/04/01 11:53
–	265	(156/345.12 156/345.13 156/345.17 156/345.18 156/345.23) and (edge peripheral periphery)	USPAT	2004/04/01 12:12
–	265	((156/345.12 156/345.13 156/345.17 156/345.18 156/345.23) and (edge peripheral periphery))	USPAT	2004/04/01 12:11
–	3116	134/1.3 134/135 134/902	USPAT	2004/04/01 12:12
–	1369	(134/1.3 134/135 134/902) and (edge peripheral periphery)	USPAT	2004/04/01 13:28
–	420	451/66 451/106 451/93	USPAT	2004/04/01 13:28
–	192	(451/66 451/106 451/93) and (edge peripheral periphery)	USPAT	2004/04/01 13:57
–	21	((polish$3 planariz$5 abrad$3) with (edge peripheral periphery)) same magnet	USPAT	2004/04/01 14:22
–	3851	magnet$6 with (polish$3 abrad$3 planari$6)	USPAT	2004/04/01 14:34
–	17	"magnetic polishing"	USPAT	2004/04/01 13:46
–	332	((polish$3 planariz$5 abrad$3) with (plurality stack) adj2 (wafers substrates))	USPAT	2004/04/01 13:56
–	248	(((polish$3 planariz$5 abrad$3) with (plurality stack) adj2 (wafers substrates))) and (edge peripheral periphery)	USPAT	2004/04/01 14:24
–	616	((polish$3 planariz$5 abrad$3) same ("synthetic resin" "chloroprene rubber"))	USPAT	2004/04/01 14:23
–	324	((polish$3 planariz$5 abrad$3) with ("synthetic resin" "chloroprene rubber"))	USPAT	2004/04/01 14:23
–	160	(((polish$3 planariz$5 abrad$3) with ("synthetic resin" "chloroprene rubber"))) and (edge peripheral periphery)	USPAT	2004/04/01 14:24
–	21	magnet$6 with (polish$3 abrad$3 planari$6)with immers$4	USPAT	2004/04/02 07:41